



DUAL SURFACE MOUNT SWITCHING DIODE

Features

- Fast Switching Speed: Maximum of 4ns
- Low Capacitance: Maximum of 2.0pF
- Small Surface Mount Package
- For General Purpose Switching Applications
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT323
- Case Material: Molded Plastic, "Green" Molding Compound, Note 5. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 Leadframe) @3
- Polarity: See Diagram
- Weight: 0.006 grams (Approximate)

Top View



Internal Schematic

Ordering Information (Notes 4 & 5)

	Part Number	Qualification	Case	Packaging		
	BAV70W-7-F	Commercial	SOT323	3,000/Tape & Reel		
	BAV70WQ-7-F	Automotive	SOT323	3,000/Tape & Reel		
Notes:	1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.					

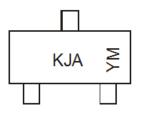
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied. 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/

5. Product manufactured with Date Code 0627 (week 27, 2006) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 0627 are built with Non-Green Molding Compound and may contain Halogens or Sb₂O₃ Fire Retardants.

Marking Information



KJA = Product Type Marking Code YM = Date Code Marking Y = Year ex: E = 2017 M = Month ex: 9 = September

Date Code Kev

Year	2000	2001	2002	2003		2013	2014	2015	2016	2017	2018	2019	2020
Code	L	М	Ν	Р		А	В	С	D	E	F	G	Н
Month	Jan	Feb	Mar	Apr	Ма	y Ji	un	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	(6	7	8	9	0	Ν	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Non-Repetitive Peak Reverse Voltage		V _{RM}	100	V	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V _{RRM} V _{RWM} VR	75	V	
RMS Reverse Voltage		V _{R(RMS)}	53	V	
Forward Continuous Current (Note 6)		I _{FM}	300	mA	
Non-Repetitive Peak Forward Surge Current (Note 6)	I _{FSM}	2.0 1.0	A		

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	PD	200	mW
Thermal Resistance Junction to Ambient Air (Note 6)	R _{0JA}	625	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-65 to +150	°C

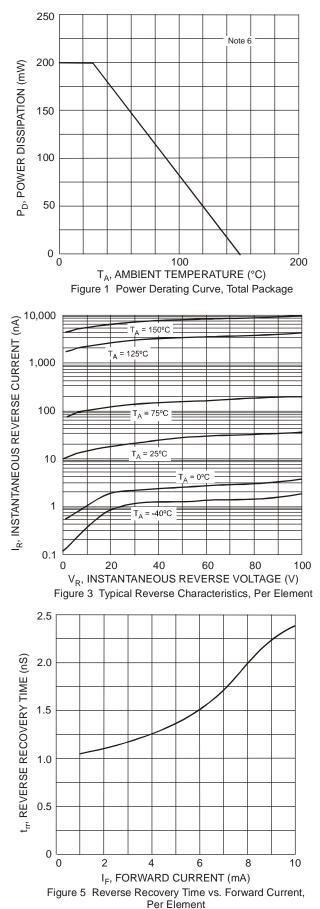
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

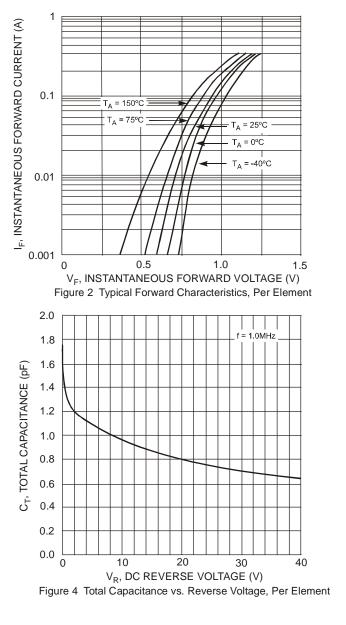
Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)		75		V	I _R = 100μΑ
Forward Voltage	VF		0.715 0.855 1.0 1.25	V	$I_{F} = 1.0mA$ $I_{F} = 10mA$ $I_{F} = 50mA$ $I_{F} = 150mA$
Reverse Current (Note 7)	I _R	_	2.5 50 30 25	μΑ μΑ μΑ nA	$V_R = 75V$ $V_R = 75V$, $T_J = +150^{\circ}C$ $V_R = 25V$, $T_J = +150^{\circ}C$ $V_R = 20V$
Total Capacitance	CT	_	2.0	pF	$V_{R} = 0, f = 1.0MHz$
Reverse Recovery Time			4.0	ns	$\begin{split} I_F &= I_R = 10 m A, \\ I_{rr} &= 0.1 \ x \ I_R, \ R_L = 100 \Omega \end{split}$

Notes:

Device mounted on a 2" x 2" Al board.
Short duration pulse test used to minimize self-heating effect.



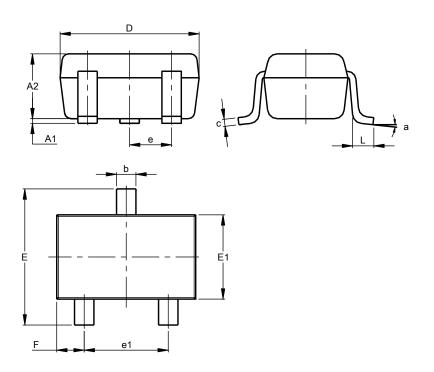






Package Outline Dimensions

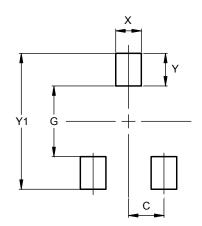
Please see http://www.diodes.com/package-outlines.html for the latest version.



SOT323								
Dim	Min	Max	Тур					
A1	0.00	0.10	0.05					
A2	0.90	1.00	0.95					
b	0.25	0.40	0.30					
С	0.10	0.18	0.11					
D	1.80	2.20	2.15					
Е	2.00	2.20	2.10					
E1	1.15	1.35	1.30					
e	0.650 BSC							
e1	1.20	1.40	1.30					
F	0.375	0.475	0.425					
L	0.25	0.40	0.30					
а	0°	8°						
All Dimensions in mm								

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
С	0.650
G	1.300
Х	0.470
Y	0.600
Y1	2.500



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